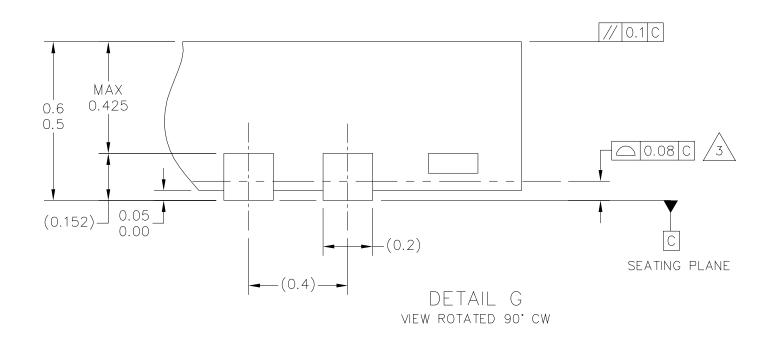


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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 20 TERMINAL, 0.4 PITCH (3 X 3 X 0.6)		DOCUMENT NO): 98ARE10742D	REV: 0
		CASE NUMBER: 2032-01		21 MAY 2008
EXPOSED LEAD END CASE		STANDARD: NO	N-JEDEC	



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		CASE NUMBER: 2032-01		21 MAY 2008
		STANDARD: NON-JEDEC		

NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3.

COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.

4.

DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 MM AND 0.25 MM FROM TERMINAL TIP.

5. MIN. METAL GAP SHOULD BE 0.2MM.

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